

and add the following in its place, immediately before the section labeled **DESCRIPTION**:

-- Related Applications

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This application is a divisional of U.S. Application Ser. No. 09/122,666, filed July 24, 1998 and issued as U.S. Patent No. 6,051,886; which is a continuation of U.S. Application Ser. No. 08/741,579, filed Nov. 1, 1996 and issued as U.S. Patent No. 5,874,781; which is a continuation of U.S. Application Ser. No. 08/515,719, filed Aug. 16, 1995 and now abandoned. --

IN THE CLAIMS:

Please amend the claims as follows.

9. (Once amended) A method of manufacturing a multichip module including dies, comprising:

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stacking all of said dies [, wherein said stacking] in a manner such that corresponding portions of any two of said dies define[s] respective axes, and wherein said axes define an offset angle [with any two of said dies]; [and]

bonding wire to said dies; and

ensuring that said step of stacking all of said dies occurs with no intervening bonding step.

10. (Once amended) [The method in claim 9,] A method of manufacturing a multichip module including dies, comprising:

stacking all of said dies, wherein corresponding portions of any two of said dies define respective axes, and wherein said axes define an offset angle; and

bonding wire to said dies;

wherein said step of stacking [further] comprises stacking all of said dies before said step of bonding wire to said dies.

11. (Once amended) [The method in claim 9,] A method of manufacturing a multichip module including dies, comprising:

stacking all of said dies, wherein corresponding portions of any two of said dies define respective axes, and wherein said axes define an offset angle; and

bonding wire to said dies;

wherein said step of bonding [further] comprises bonding all of said wire only after said step of stacking all of said dies.

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cont

12. (Once amended) A method of assembling a plurality of dies, comprising:

stacking said plurality of dies along an axis;

establishing an orientation for each die of said plurality of dies;

marginally clearing a line of sight to contact areas of any immediately underlying die with said orientation [of] for said each die, wherein said line of sight is parallel to said axis; and

clearing [said] a line of sight to contact areas of any underlying die with said orientation [of] for said each die.

13. (Once amended) A method of stacking a plurality of chips

spiraling said plurality of chips around an axis perpendicular to said plurality of chips;  
and

ensuring at most a minimum bond pad clearance to each chip of said plurality of chips.

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16. (Once amended) The method in claim 15, wherein said ensuring step [of ensuring bond pad clearance further] comprises rotating a chip around said axis at least to [the] an extent that a bond pad on an underlying chip is exposed.